

SFF50N20N
SFF50N20P

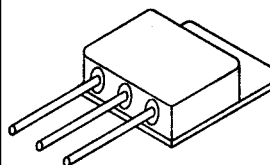
Designer's Data Sheet

FEATURES:

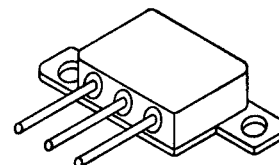
- Rugged construction with polysilicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Ceramic Seals for improved hermeticity
- Hermetically sealed package
- TX, TXV and Space Level screening available
- Replaces: IXTH50N20 Types

50 AMP
200 VOLTS
0.055 Ω
N-CHANNEL
POWER MOSFET

TO-258 (N)



TO-259 (P)



MAXIMUM RATINGS:

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V _{DS}	200	Volts
Gate to Source Voltage	V _{GS}	±20	Volts
Continuous Drain Current	I _D	50	Amps
Operating and Storage Temperature	Top & Tstg	-55 to +150	°C
Thermal Resistance, Junction to Case	R _{θJC}	0.83	°C/W
Total Device Dissipation @ TC=25°C	P _D	150	Watts
Total Device Dissipation @ TC=55°C		114	

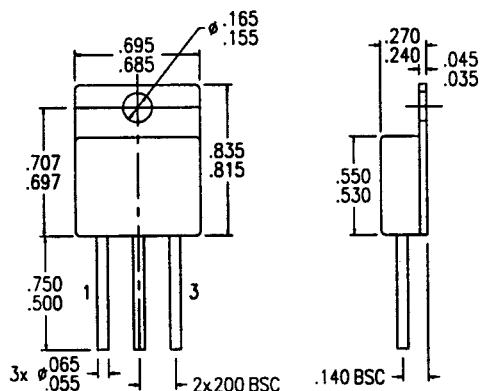
PACKAGE OUTLINE: TO-258 (N)

PIN OUT:

PIN 1: DRAIN

PIN 2: SOURCE

PIN 3: GATE



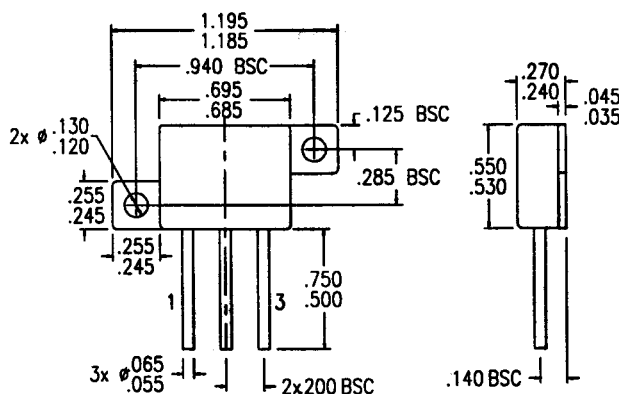
PACKAGE OUTLINE: TO-259 (P)

PIN OUT:

PIN 1: DRAIN

PIN 2: SOURCE

PIN 3: GATE



NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: F00133 B

MED

SFF50N20N SFF50N20P

PRELIMINARY



SOLID STATE DEVICES, INC

14849 Firestone Boulevard · La Mirada, CA 90638
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

ELECTRICAL CHARACTERISTICS @ $T_J=25^\circ\text{C}$ (Unless Otherwise Specified)

RATING	SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage ($V_{GS}=0\text{ V}$, $I_D=250\mu\text{A}$)	BV_{DSS}	200	---	---	V
Drain to Source on State Resistance ($V_{GS}=10\text{ V}$, $I_D=60\%$ Rated ID)	$R_{DS(on)}$	---	---	0.055	Ω
On State Drain Current ($V_{DS}>I_D(on) \times R_{DS(on)}$ Max, $V_{GS}=10\text{ V}$)	$I_D(on)$	50	---	---	A
Gate Threshold Voltage ($V_{DS}=V_{GS}$, $I_D=4\text{mA}$)	$V_{GS(th)}$	2.0	---	4.0	V
Forward Transconductance ($V_{DS}>I_D(on) \times R_{DS(on)}$ Max, $I_{DS}=50\%$ rated ID)	g_{fs}	20	25	---	S(Ω)
Zero Gate Voltage Drain Current ($V_{DS}=\text{max rated voltage}$, $V_{GS}=0\text{ V}$) ($V_{DS}=80\%$ rated V_{DS} , $V_{GS}=0\text{ V}$, $T_A=125^\circ\text{C}$)	I_{DSS}	---	---	250 1000	μA
Gate to Source Leakage Forward Gate to Source Leakage Reverse	At rated V_{GS} I_{GSS}	---	---	+100 -100	nA
Total Gate Charge Gate to Source Charge Gate to Drain Charge	$V_{GS}=10\text{ Volts}$ 50% rated V_{DS} 50% Rated ID Q_g Q_{gs} Q_{gd}	---	190 35 95	220 50 120	nC
Turn on Delay Time Rise Time Turn Off Delay Time Fall Time	$V_{DD}=50\%$ rated V_{DS} 50% rated ID $R_G=6.2\Omega$ $V_{GS}=10\text{V}$ $t_d(on)$ t_r $t_d(off)$ t_f	---	28 33 110 30	35 40 130 35	nsec
Diode Forward Voltage ($I_S=\text{rated ID}$, $V_{GS}=0\text{ V}$, $T_J=25^\circ\text{C}$)	V_{SD}	---	---	1.5	V
Diode Reverse Recovery Time Reverse Recovery Charge	$T_J=25^\circ\text{C}$ $I_F=10\text{ A}$ $dI/dt=100\text{ A}/\mu\text{sec}$ t_{rr} Q_{RR}	---	---	225 ---	nsec μC
Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{GS}=0\text{ Volts}$ $V_{DS}=25\text{ Volts}$ $f=1\text{ MHz}$ C_{iss} C_{oss} C_{rss}	---	4400 800 285	---	pF

SAFE OPERATING AREA (S.O.A.)
 $T_C = 25^\circ\text{C}$, D.C. CONDITION

